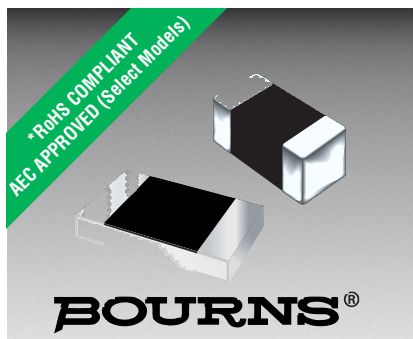




Features

- Select models are compliant with AEC-Q200 Rev-C Stress Test Qualification for Passive Components in Automotive Applications (see chart below)
- RoHS compliant*
- ESD protection >25 kV
- Low capacitance <0.05 pF
- Low leakage current <5 nA

Applications

- HDMI 1.4
- Digital Visual Interface (DVI)
- USB 3.0 / USB OTG
- Memory protection
- SIM card ports
- Automotive

ChipGuard® MLU Series - ESD Protectors

General Information

The ChipGuard® MLU Series has been specifically designed to protect sensitive electronic components from electrostatic discharge damage. The MLU family has been designed to protect equipment to IEC61000-4-2, Level 4 (±8 kV Contact / ±15 kV Air Discharge) ESD specifications targeted for high speed USB 3.0/USB OTG, HDMI 1.4, DVI or IEEE1394 applications.

The ChipGuard® MLU Series has been manufactured to provide low 0.05 pF capacitance and leakage currents less than 5 nA with excellent clamp qualities, making the family almost transparent under normal working conditions.

AEC Approved Models

Model	AEC-Q200
CG0402MLU-05G	✓ Yes
CG0402MLU-12G	✓ Yes
CG0402MLU-24G	✓ Yes
CG0603MLU-05E	✓ Yes
CG0603MLU-24E	✓ Yes

Device Symbol



Electrical Characteristics @ 25 °C (unless otherwise noted)

Parameter	Symbol	CG0402MLU / CG0603MLU (Note 3)				Unit
		3.3x	05x	12x	24x	
Typical Continuous Operating Voltage	V _{DC}	3.3	5	12	24	V
Typical Clamping Voltage (Note 1)	V _C	25				V
Maximum Capacitance @ 1 VRMS 1 MHz	C _O	0.05				pF
Maximum Leakage Current @ Max. VDC	I _L	5				nA
Typical Trigger Voltage (Note 2)	V _T	250				V
Maximum ResponseTime	R _T	1				ns
ESD Protection: Per IEC 61000-4-2 Min. Contact Discharge (>1000 Reps) Min. Air Discharge (>1000 Reps)		±8 ±15				kV kV
Operating Temperature	T _{OPR}	-40 to +125				°C
Storage Temperature	T _{STG}	-55 to +150				°C

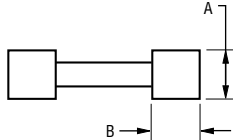
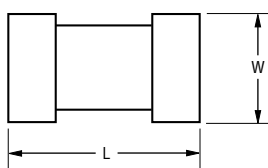
Notes: 1. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement 30 ns after initiation of pulse.
2. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement at maximum pulse voltage.
3. Part number suffix "x" can be E for 0603 size or G for 0402 size to indicate tape & reel quantity.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.
Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

ChipGuard® MLU Series - ESD Protectors

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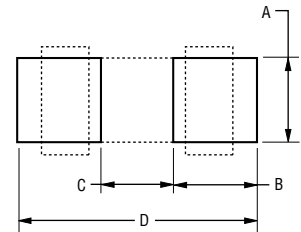
Product Dimensions



DIMENSIONS: $\frac{\text{MM}}{(\text{INCHES})}$

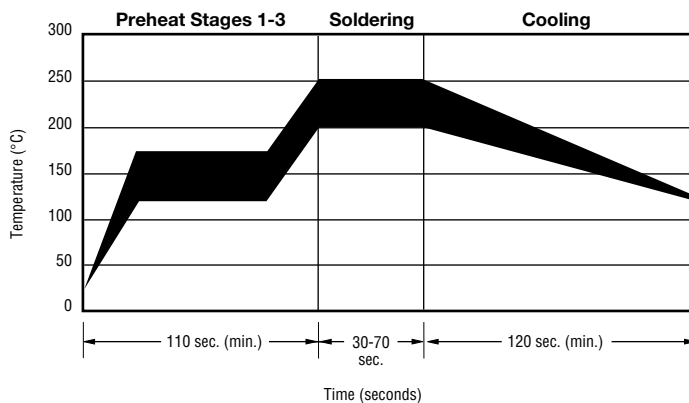
Dimension	CG0402 Series	CG0603 Series
L	$\frac{1.00 \pm 0.15}{(0.04 \pm 0.006)}$	$\frac{1.60 \pm 0.20}{(0.064 \pm 0.008)}$
W	$\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$	$\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$
A	$\frac{0.36 \pm 0.05}{(0.014 \pm 0.002)}$	$\frac{0.45 \pm 0.10}{(0.018 \pm 0.004)}$
B	$\frac{0.25 \pm 0.15}{(0.10 \pm 0.006)}$	$\frac{0.30 \pm 0.20}{(0.012 \pm 0.008)}$

Recommended Pad Layout



Dim.	CG0402 Series	CG0603 Series
A	$\frac{0.51}{(0.020)}$	$\frac{0.76}{(0.030)}$
B	$\frac{0.61}{(0.024)}$	$\frac{1.02}{(0.040)}$
C	$\frac{0.51}{(0.020)}$	$\frac{0.50}{(0.020)}$
D	$\frac{1.70}{(0.067)}$	$\frac{2.54}{(0.100)}$

Solder Reflow Recommendations



A	Stage 1 Preheat	Ambient to Preheating Temperature	30 s to 60 s
B	Stage 2 Preheat	140 °C to 160 °C	60 s to 120 s
C	Stage 3 Preheat	Preheat to 200 °C	20 s to 40 s
D	Main Heating	200 °C 210 °C 220 °C 230 °C 240 °C	60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s
E	Cooling	200 °C to 100 °C	1 °C/s to 4 °C/s

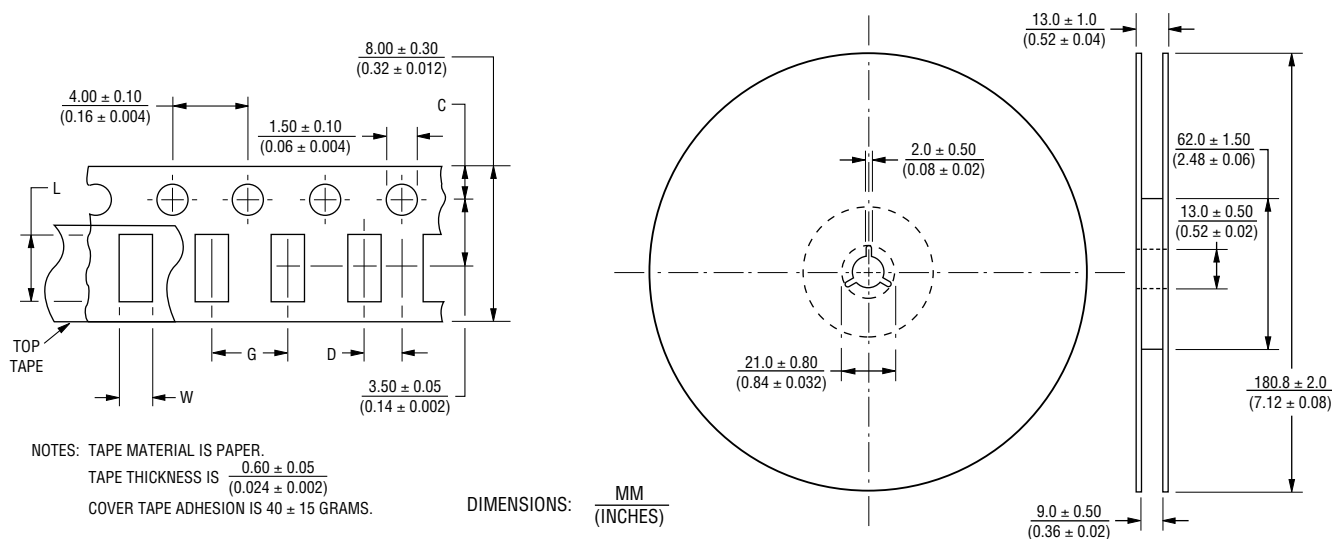
- This product can be damaged by rapid heating, cooling or localized heating.
- Heat shocks should be avoided. Preheating and gradual cooling recommended.
- Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.
- Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds. A solder gun under 30 watts is recommended.

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ChipGuard® MLU Series - ESD Protectors

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Packaging Dimensions



Dimension	CG0402 Series	CG0603 Series
C	$\frac{1.75 \pm 0.05}{(0.04 \pm 0.002)}$	$\frac{1.75 \pm 0.10}{(0.04 \pm 0.004)}$
D	$\frac{2.00 \pm 0.02}{(0.08 \pm 0.0008)}$	$\frac{2.00 \pm 0.05}{(0.08 \pm 0.002)}$
L	$\frac{1.12 \pm 0.03}{(0.045 \pm 0.0012)}$	$\frac{1.80 \pm 0.20}{(0.072 \pm 0.008)}$
W	$\frac{0.62 \pm 0.03}{(0.025 \pm 0.0012)}$	$\frac{0.90 \pm 0.20}{(0.036 \pm 0.008)}$
G	$\frac{2.0 \pm 0.05}{(0.08 \pm 0.002)}$	$\frac{4.0 \pm 0.05}{(0.16 \pm 0.002)}$

How to Order

CG 0n0n MLU - n.n x

ChipGuard®
Product Designator
Package Option
0402 = 0402 Package
0603 = 0603 Package
Multilayer Series Designator
Operating Voltage**
3.3 = 3.3 V
05 = 5 V
12 = 12 V
24 = 24 V
Tape & Reel Packaging
E = 5,000 pcs. per reel (0603 Package)
G = 10,000 pcs. per reel (0402 Package)

** Only models lower than 10 volts require decimal point.

REV. J 09/12

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Asia-Pacific: Tel: +886-2 2562-4117 • Fax: +886-2 2562-4116

Europe: Tel: +41-41 768 5555 • Fax: +41-41 768 5510

The Americas: Tel: +1-951 781-5500 • Fax: +1-951 781-5700

www.bourns.com